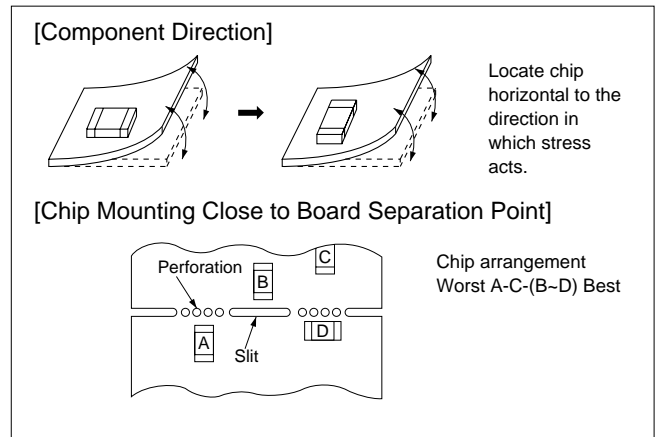


⚠ Caution

■ Soldering and Mounting

1. Mounting Position

1. Confirm the best mounting position and direction that minimizes the stress imposed on the capacitor during flexing or bending the printed circuit board.
 - 1-1. Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.



2. Information before Mounting

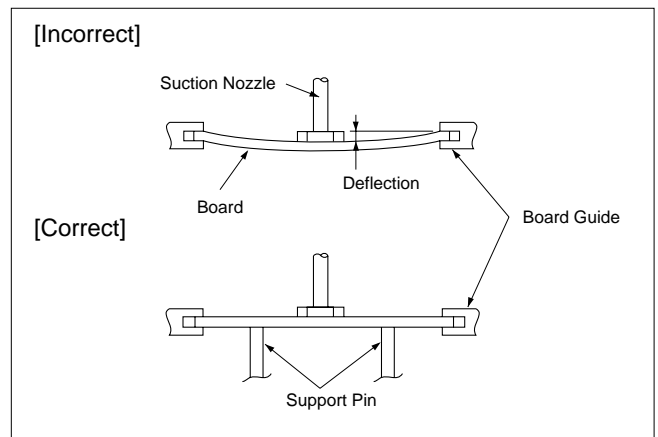
1. Do not re-use capacitors that were removed from the equipment.
2. Confirm capacitance characteristics under actual applied voltage.
3. Confirm the mechanical stress under actual process and equipment use.
4. Confirm the rated capacitance, rated voltage and other electrical characteristics before assembly.

5. Prior to use, confirm the Solderability for the capacitors that were in long-term storage.
6. Prior to measuring capacitance, carry out a heat treatment for capacitors that were in long-term storage.
7. The use of Sn-Zn based solder will deteriorate the reliability of the MLCC.

Please contact our sales representative or product engineers on the use of Sn-Zn based solder in advance.

3. Maintenance of the Mounting (pick and place) Machine

1. Make sure that the following excessive forces are not applied to the capacitors.
 - 1-1. In mounting the capacitors on the printed circuit board, any bending force against them shall be kept to a minimum to prevent them from any bending damage or cracking. Please take into account the following precautions and recommendations for use in your process.
 - (1) Adjust the lowest position of the pickup nozzle so as not to bend the printed circuit board.
 - (2) Adjust the nozzle pressure within a static load of 1N to 3N during mounting.
2. Dirt particles and dust accumulated between the suction nozzle and the cylinder inner wall prevent the nozzle from moving smoothly. This imposes greater force upon the chip during mounting, causing cracked chips. Also the locating claw, when worn out, imposes uneven forces on the chip when positioning, causing cracked chips. The suction nozzle and the locating claw must be maintained, checked and replaced periodically.



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Caution

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4-1. Reflow Soldering

- When sudden heat is applied to the components, the mechanical strength of the components will decrease because a sudden temperature change causes deformation inside the components. In order to prevent mechanical damage to the components, preheating is required for both the components and the PCB board. Preheating conditions are shown in table 1. It is required to keep the temperature differential between the solder and the components surface (ΔT) as small as possible.
- Solderability of Tin plating termination chips might be deteriorated when a low temperature soldering profile where the peak solder temperature is below the melting point of Tin is used. Please confirm the Solderability of Tin plated termination chips before use.
- When components are immersed in solvent after mounting, be sure to maintain the temperature difference (ΔT) between the component and the solvent within the range shown in the table 1.

Table 1

Part Number	Temperature Differential
GRM02/03/15/18/21/31 GJM03/15 LLL15/18/21/31 ERB18/21 GQM18/21	$\Delta T \leq 190^\circ\text{C}$
GRM32/43/55 LLA18/21/31 LLM21/31 GNM ERB32	$\Delta T \leq 130^\circ\text{C}$

Recommended Conditions

	Pb-Sn Solder		Lead Free Solder
	Infrared Reflow	Vapor Reflow	
Peak Temperature	230 to 250°C	230 to 240°C	240 to 260°C
Atmosphere	Air	Air	Air or N ₂

Pb-Sn Solder: Sn-37Pb

Lead Free Solder: Sn-3.0Ag-0.5Cu

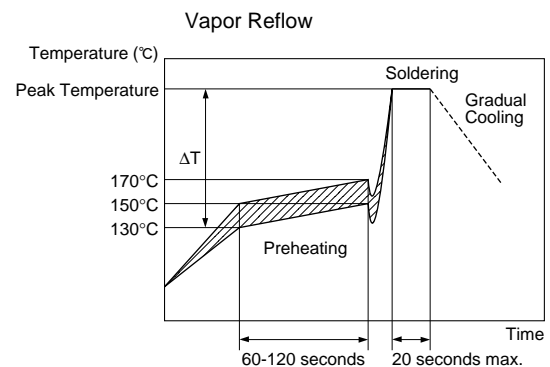
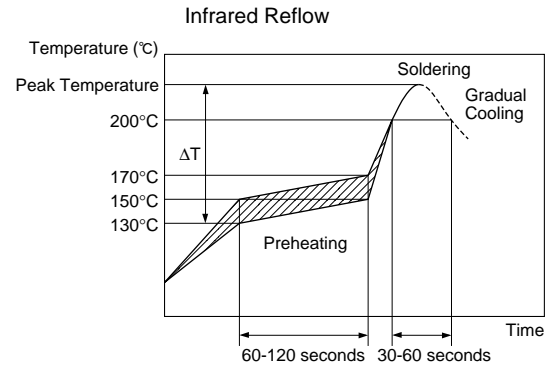
4. Optimum Solder Amount for Reflow Soldering

- Overly thick application of solder paste results in a excessive solder fillet height. This makes the chip more susceptible to mechanical and thermal stress on the board and may cause the chips to crack.
- Too little solder paste results in a lack of adhesive strength on the outer electrode, which may result in chips breaking loose from the PCB.
- Make sure the solder has been applied smoothly to the end surface to a height of 0.2mm* min.

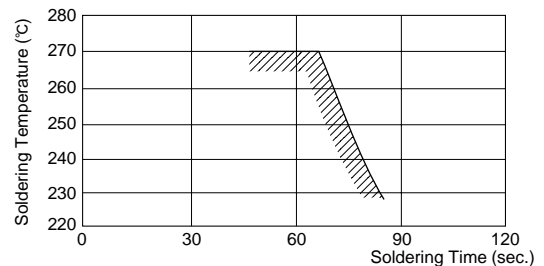
Inverting the PCB

Make sure not to impose any abnormal mechanical shocks to the PCB.

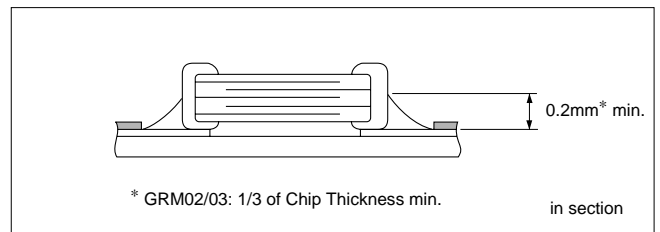
[Standard Conditions for Reflow Soldering]



[Allowable Reflow Soldering Temperature and Time]



In case of repeated soldering, the accumulated soldering time must be within the range shown above.



⚠ Caution

☐ Continued from the preceding page.

4-2. Flow Soldering

- When sudden heat is applied to the components, the mechanical strength of the components will decrease because a sudden temperature change causes deformation inside the components. In order to prevent mechanical damage in the components, preheating should be required for both of the components and the PCB board.
Preheating conditions are shown in table 2. It is required to keep temperature differential between the solder and the components surface (ΔT) as small as possible.
- Excessively long soldering time or high soldering temperature can result in leaching of the outer electrodes, causing poor adhesion or a reduction in capacitance value due to loss of contact between electrodes and end termination.
- When components are immersed in solvent after mounting, be sure to maintain the temperature difference (ΔT) between the component and solvent within the range shown in the table 2.
- Do not apply flow soldering to chips not listed in table 2.

Table 2

Part Number	Temperature Differential
GRM18/21/31	$\Delta T \leq 150^\circ\text{C}$
LLL21/31	
ERB18/21	
GQM18/21	

Recommended Conditions

	Pb-Sn Solder	Lead Free Solder
Preheating Peak Temperature	90 to 110°C	100 to 120°C
Soldering Peak Temperature	240 to 250°C	250 to 260°C
Atmosphere	Air	N ₂

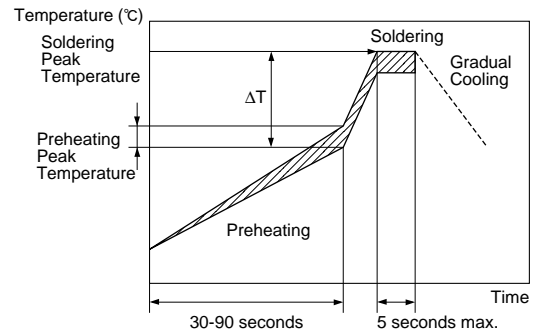
Pb-Sn Solder: Sn-37Pb

Lead Free Solder: Sn-3.0Ag-0.5Cu

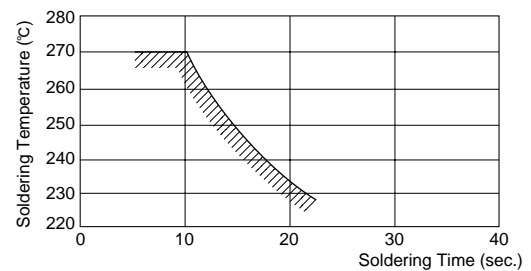
5. Optimum Solder Amount for Flow Soldering

- The top of the solder fillet should be lower than the thickness of components. If the solder amount is excessive, the risk of cracking is higher during board bending or any other stressful condition.

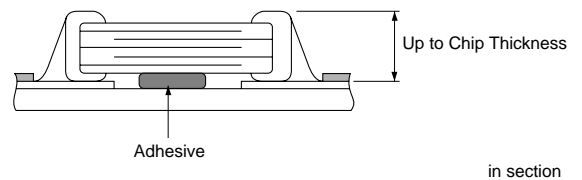
[Standard Conditions for Flow Soldering]



[Allowable Flow Soldering Temperature and Time]



In case of repeated soldering, the accumulated soldering time must be within the range shown above.



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⚠ Caution

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4-3. Correction with a Soldering Iron

1. When sudden heat is applied to the components when using a soldering iron, the mechanical strength of the components will decrease because the extreme temperature change can cause deformations inside the components. In order to prevent mechanical damage to the components, preheating is required for both the components and the PCB board. Preheating conditions, (The "Temperature of the Soldering Iron Tip", "Preheating Temperature", "Temperature Differential" between the iron tip and the components and the PCB), should be within the conditions of table 3. It is required to keep the temperature differential between the soldering iron and the component surfaces (ΔT) as small as possible.
2. After soldering, do not allow the component/PCB to rapidly cool down.
3. The operating time for the re-working should be as short as possible. When re-working time is too long, it may cause solder leaching, and that will cause a reduction in the adhesive strength of the terminations.
4. Optimum Solder amount when re-working with a Soldering Iron
 - 4-1. In case of sizes smaller than 0603, (GRM03/15/18, GJM03/15, GQM18, ERB18), the top of the solder fillet should be lower than 2/3's of the thickness of the component or 0.5mm whichever is smaller. In case of 0805 and larger sizes, (GRM21/31/32/43/55, GQM21, ERB21/32), the top of the solder fillet should be lower than 2/3's of the thickness of the component. If the solder amount is excessive, the risk of cracking is higher during board bending or under any other stressful condition.
 - 4-2. A soldering iron with a tip of $\varnothing 3\text{mm}$ or smaller should be used. It is also necessary to keep the soldering iron from touching the components during the re-work.
 - 4-3. Solder wire with $\varnothing 0.5\text{mm}$ or smaller is required for soldering.

4-4. Leaded Component Insertion

1. If the PCB is flexed when leaded components (such as transformers and ICs) are being mounted, chips may crack and solder joints may break.
Before mounting leaded components, support the PCB using backup pins or special jigs to prevent warping.

5. Washing

Excessive ultrasonic oscillation during cleaning can cause the PCBs to resonate, resulting in cracked chips or broken solder joints. Take note not to vibrate PCBs.

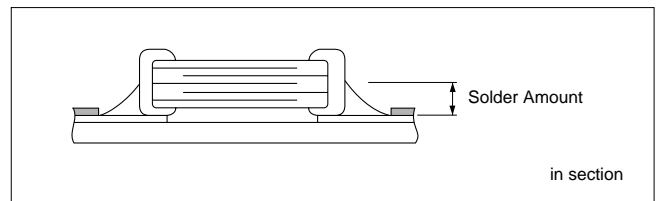
Table 3

Part Number	Temperature of Soldering Iron Tip	Preheating Temperature	Temperature Differential (ΔT)	Atmosphere
GRM03/15/18/21/31 GJM03/15 GQM18/21 ERB18/21	350°C max.	150°C min.	$\Delta T \leq 190^\circ\text{C}$	Air
GRM32/43/55 ERB32	280°C max.	150°C min.	$\Delta T \leq 130^\circ\text{C}$	Air

*Applicable for both Pb-Sn and Lead Free Solder.

Pb-Sn Solder: Sn-37Pb

Lead Free Solder: Sn-3.0Ag-0.5Cu



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⚠ Caution

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6. Electrical Test on Printed Circuit Board

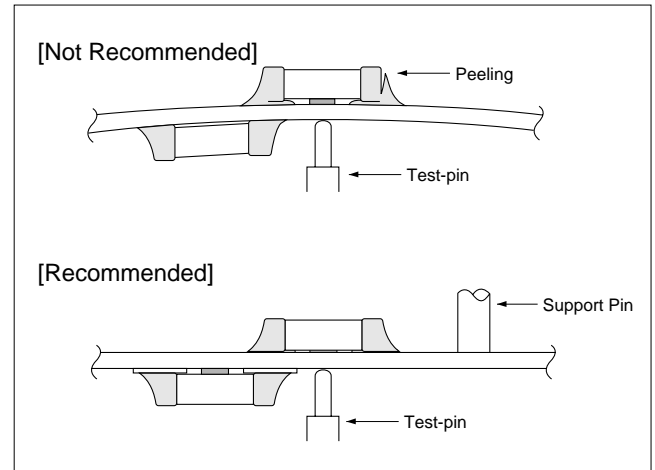
1. Confirm position of the support pin or specific jig, when inspecting the electrical performance of a capacitor after mounting on the printed circuit board.

1-1. Avoid bending printed circuit board by the pressure of a test pin, etc.

The thrusting force of the test probe can flex the PCB, resulting in cracked chips or open solder joints.

Provide support pins on the back side of the PCB to prevent warping or flexing.

1-2. Avoid vibration of the board by shock when a test pin contacts a printed circuit board.

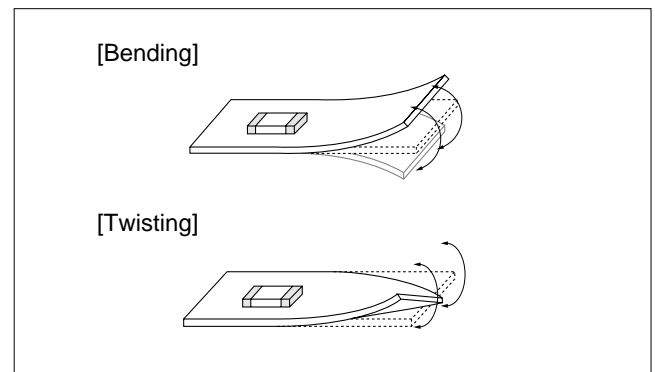


7. Printed Circuit Board Cropping

1. After mounting a capacitor on a printed circuit board, do not apply any stress to the capacitor that is caused by bending or twisting the board.

1-1. In cropping the board, the stress as shown right may cause the capacitor to crack.

Try not to apply this type of stress to a capacitor.



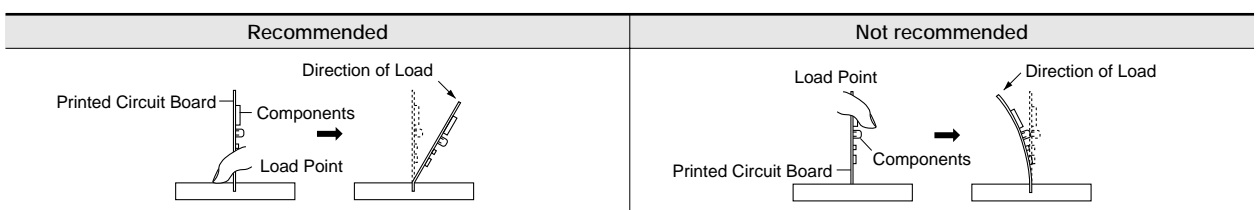
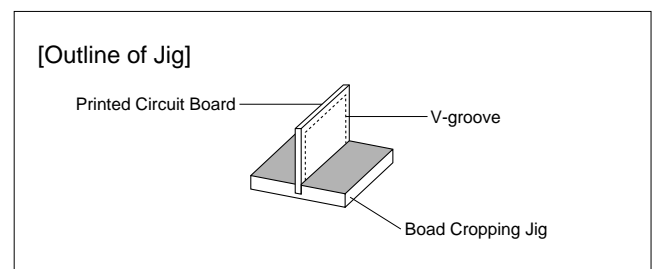
2. Check of the cropping method for the printed circuit board in advance.

2-1. Printed circuit board cropping shall be carried out by using a jig or an apparatus to prevent the mechanical stress which can occur to the board.

(1) Example of a suitable jig

Recommended example: the board should be pushed as close to the near the cropping jig as possible and from the back side of board in order to minimize the compressive stress applied to capacitor.

Not recommended example* when the board is pushed at a point far from the cropping jig and from the front side of board as below, the capacitor may form a crack caused by the tensile stress applied to capacitor.



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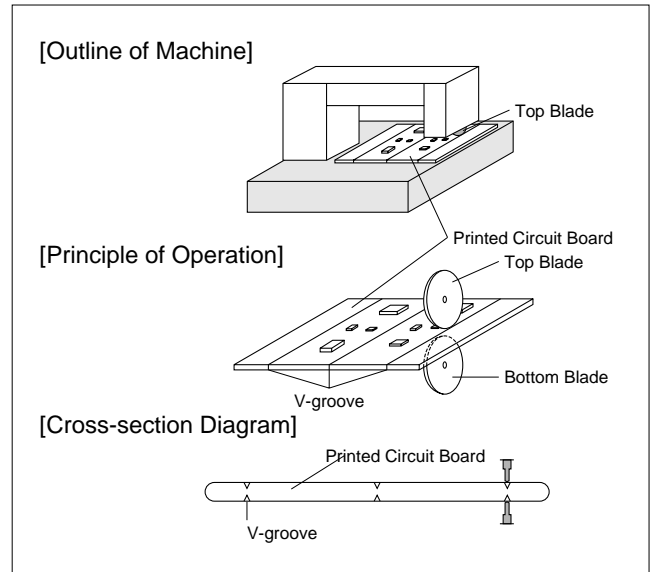
⚠ Caution

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(2) Example of a suitable machine

An outline of a printed circuit board cropping machine is shown as follows. Along the lines with the V-grooves on printed circuit board, the top and bottom blades are aligned to one another when cropping the board.

The misalignment of the position between top and bottom blades may cause the capacitor to crack.



Recommended	Not Recommended		
	Top-bottom Misalignment	Left-right Misalignment	Front-rear Misalignment
<p>Top Blade</p> <p>Bottom Blade</p>	<p>Top Blade</p> <p>Bottom Blade</p>	<p>Top Blade</p> <p>Bottom Blade</p>	<p>Top Blade</p> <p>Bottom Blade</p>